

L Number	Hits	Search Text	DB	Time stamp
34	3	c23c016\$.ipc. and (dry\$3 with heat\$3 with compress\$3 with air)	USPAT; US-PGPUB	2004/09/29 16:54
36	10	118/\$.ccls. and (dry\$3 with heat\$3 with compress\$3 with air)	USPAT; US-PGPUB	2004/09/29 16:55
35	1	c23c016\$.ipc. and (dry\$3 with heat\$3 with compress\$3 with air)	EPO; JPO; DERWENT	2004/09/29 16:55
37	5	(wafer substrate workpiece semiconductor) and (clean\$3 wash\$3) and (dry\$3 with heat\$3 with compress\$3 with air)	EPO; JPO; DERWENT	2004/09/29 16:55
39	97	(wafer substrate workpiece semiconductor) and (clean\$3 wash\$3) and (dry\$3 with heat\$3 with compress\$3 with air)	USPAT; US-PGPUB	2004/09/29 16:56
40	11	(wafer substrate workpiece semiconductor) same (clean\$3 wash\$3) same (dry\$3 with heat\$3 with compress\$3 with air)	USPAT; US-PGPUB	2004/09/29 16:56
38	5	(wafer substrate workpiece semiconductor) and (clean\$3 wash\$3) and (dry\$3 with heat\$3 with compress\$3 with air)	EPO; JPO; DERWENT	2004/09/29 16:58
-	1775	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2004/09/29 16:53
-	289	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((wash\$3 clean\$3) same (dry\$3 heat\$3) same (etch\$3 deposit\$3 coat\$3))	USPAT; US-PGPUB	2003/09/26 16:18
-	25	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((wash\$3 clean\$3) same (dry\$3 heat\$3) same (etch\$3 deposit\$3 coat\$3))) and 118/718.ccls.	USPAT; US-PGPUB	2003/09/26 16:07
-	3	5356474.URPN.	USPAT	2003/09/26 16:13
-	22	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((wash\$3 clean\$3) with (solution fluid)) same (dry\$3 heat\$3) same (etch\$3 deposit\$3 coat\$3))	USPAT; US-PGPUB	2003/09/26 16:34
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (brush\$3 same rins\$3 same ultrasonic\$3)	USPAT; US-PGPUB	2003/09/26 16:20
-	148	brush\$3 same rins\$3 same ultrasonic\$3	USPAT; US-PGPUB	2003/09/26 16:20
-	3	(brush\$3 same rins\$3 same ultrasonic\$3) and (118/\$.ccls. 156/345\$.ccls.)	USPAT; US-PGPUB	2003/09/26 16:21
-	11	("1289507" "3294576" "3367791" "3429741" "3473955" "3535157" "3589975" "3756196" "4004045" "4114563" "4154193").PN.	USPAT	2003/09/26 16:26
-	1	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (air with knife with (plural\$3 multiple))	USPAT; US-PGPUB	2003/09/26 16:36
-	39	(118/\$.ccls. 156/345\$.ccls.) and (air with knife with (plural\$3 multiple))	USPAT; US-PGPUB	2003/09/26 16:36
-	0	(c23c016\$.ipc.) and (air with knife with (plural\$3 multiple))	EPO; JPO; DERWENT	2003/09/26 16:38
-	26	4370356.URPN.	USPAT	2003/09/26 16:36
-	1	(c23c016\$.ipc.) and (air with knife)	EPO; JPO; DERWENT	2003/09/26 18:38
-	48	(air with knife with (plural\$3 multiple))	EPO; JPO; DERWENT	2003/09/26 16:47
-	0	((air with knife with (ion\$5))) and ((air with knife with (heat\$3)))	EPO; JPO; DERWENT	2003/09/26 16:47
-	13	(air with knife with (ion\$5))	EPO; JPO; DERWENT	2003/09/26 16:50
-	0	((air with knife with (ion\$5))) and ((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.)	USPAT; US-PGPUB	2003/09/26 16:51
-	3	((air with knife with (ion\$5))) and (118/\$.ccls. 156/345\$.ccls.)	USPAT; US-PGPUB	2003/09/26 16:51
-	142	(air with knife with (heat\$3))	EPO; JPO; DERWENT	2003/09/26 16:57
-	1	("4017982").PN.	USPAT; US-PGPUB	2003/09/26 16:57

-	212	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (load with lock\$3 with chamber) and (clean\$3 with chamber)	USPAT; US-PGPUB	2003/09/26 16:59
-	41	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (load with lock\$3 with chamber with heat\$3) and (clean\$3 with chamber)	USPAT; US-PGPUB	2003/09/26 17:12
-	79	kondo-masataka\$.in. hayashi-katsuhiko.in. kuribe-eiji.in.	USPAT; US-PGPUB	2003/09/26 17:13
-	17	(kondo-masataka\$.in. hayashi-katsuhiko.in. kuribe-eiji.in.) and (clean\$3 wash\$3 rins\$3)	USPAT; US-PGPUB	2003/09/26 17:19
-	3	(("6103442") or ("5587226") or ("5501744")).PN.	USPAT; US-PGPUB	2003/09/26 17:19
-	2	("10209477").PN.	JPO; DERWENT	2003/09/26 17:20
-	60	(air with knife with (ion\$5))	USPAT; US-PGPUB	2003/09/26 18:16
-	611	(c23c016\$.ipc.) and ((film layer coat\$3) and ((material process) with gas) and (inert with gas))	EPO; JPO; DERWENT	2003/09/26 18:39
-	69	(c23c016\$.ipc.) and ((film layer coat\$3) and ((material process) with gas) and (inert with gas) and pipe)	EPO; JPO; DERWENT	2003/09/26 18:39
-	22	(c23c016\$.ipc.) and ((film layer coat\$3) and ((material process) with gas) and (inert with gas) and pipe and plasma)	EPO; JPO; DERWENT	2003/09/26 18:39